MA3X717 (MA717)

Silicon epitaxial planar type

For switching

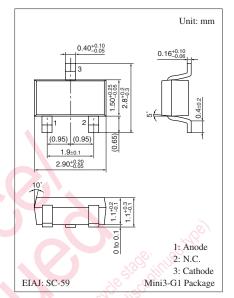
For wave detection

Features

- \bullet Low forward voltage $V_{\rm F}$, optimum for low voltage rectification
- Low V_F type of MA3X704A (MA704A)
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

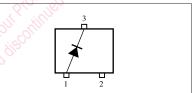
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Parameter	Symbol	Rating	Unit				
Reverse voltage	V _R	30	V				
Maximum peak reverse voltage	V _{RM}	30	V				
Peak forward current	I _{FM}	150	mA				
Forward current	$I_{\rm F}$	30	mA				
Junction temperature	Tj	125	°Ċ				
Storage temperature	T _{stg}	-55 to +125	°C				

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: M2M

Internal Connection

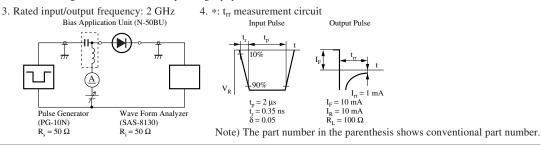


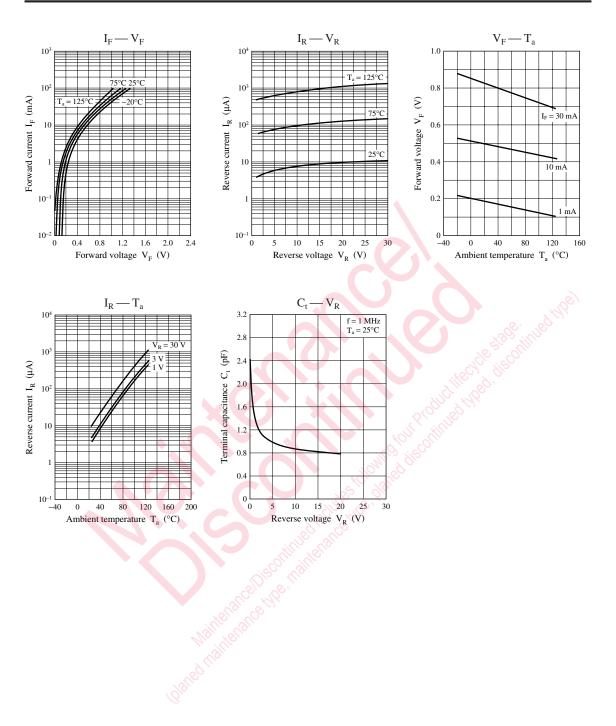
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 1 \text{ mA}$			0.3	V
	V _{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	IR	$V_R = 30 V$			30	μΑ
Terminal capacitance	Ct	$V_R = 1 V, f = 1 MHz$		1.5		pF
Reverse recovery time *	t _r	$I_F = I_R = 10 \text{ mA}$		1.0		ns
	Nghi Cho	$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	n	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz		65		%
	96.	$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.





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